

AOS Semiconductor Product Reliability Report



Plastic Encapsulated Device

ALPHA & OMEGA Semiconductor, Inc

www.aosmd.com

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This AOS product reliability report summarizes the qualification result for AOI4N60. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOI4N60 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

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Test Item	Test Condition	Time Point	Total Sample Size	Number of Failures	Reference Standard
HTGB	Temp = 150°C 168 / 500 / 924 pcs Vgs=100% of Vgsmax 1000 hours 924 pcs		924 pcs	0	JESD22-A108
HTRB	Temp = 150°C, Vds=80% of Vdsmax	168 / 500 / 1000 hours	924 pcs	0	JESD22-A108
Precondition (Note A)	168hr 85°C / 85%RH + 3 cycle reflow@260°C (MSL 1)	-	4620 pcs	0	JESD22-A113
HAST	130°C , 85%RH, 33.3 psia, Vds = 80% of Vdsmax up to 42V	96 hours	693 pcs	0	JESD22-A110
H3TRB	85°C , 85%RH, Vds = 80% of Vdsmax up to 100V	1000 hours	693 pcs	0	JESD22-A101
Autoclave	121°C , 29.7psia, RH=100%	96 hours	924 pcs	0	JESD22-A102
Temperature Cycle	-65°C to 150°C, air to air,	1000cycles	924 pcs	0	JESD22-A104
HTSL	Temp = 150°C	1000 hours	693 pcs	0	JESD22-A103
IOL	∆ Tj = 100°C	15000 cycles	693 pcs	0	MIL-STD-750 Method 1037

I. Reliability Stress Test Summary and Results

Note: The reliability data presents total of available generic data up to the published date. Note A: MSL (Moisture Sensitivity Level) 1 based on J-STD-020

II. Reliability Evaluation

FIT rate (per billion): 1.91 MTTF = 59839 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

Failure Rate = $\text{Chi}^2 \times 10^9 / [2 \text{ (N) (H) (Af)}] = 1.91$

MTTF = 10^9 / FIT = 59839 years

 Chi^2 = Chi Squared Distribution, determined by the number of failures and confidence interval N = Tatal Number of units from hum in tests.

- N = Total Number of units from burn-in tests
- **H** = Duration of burn-in testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = $55^{\circ}C$)

Acceleration Factor [Af] = Exp [Ea / k (1/Tj u - 1/Tj s)]

Acceleration Factor ratio list:

Af 259 87 32 13 5.64 2.59 1		55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
	Af	259	87	32	13	5.64	2.59	1

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

Tj u =The use junction temperature in degree (Kelvin), K = C+273.16

 \mathbf{k} = Boltzmann's constant, 8.617164 X 10⁻⁵ eV / K